

Please amend Claim 8 as follows:

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8. The package as claimed in Claim 7 wherein a plurality of fingers extend from each of said sides.

Please amend Claim 11 as follows:

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11. A peripheral device PCB package comprising:
two stamped metal covers having a first side and a second side with at least one finger extending from each of said sides of each cover; and
a plastic frame element associated with each of the covers, wherein edges of the metal covers are bent to conform to a shape of the frame and the plastic frame elements are injection molded to secure the fingers of each cover to the plastic frame element.

Please amend Claim 18 as follows:

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18. A PCB package comprising:
a first package half including a stamped metal cover and a frame element, said cover having an edge bent to conform to a shape of said frame in a generally U-shaped configuration with said frame element being injection molded within the U-shaped edge of the metal cover;
a second package half including a stamped metal cover and an injection molded frame element attached to the metal cover; and
the first package half sonically bonded to the second package half.

Please amend claims 19 and 21 as follows:

19. The package as claimed in Claim 18 wherein the frame element of the first package half includes a plastic

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perimeter surface with a raised surface to facilitate bonding with the second package half.

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21. The package as claimed in Claim 19 wherein the frame element of the second package half includes a plastic perimeter surface with a groove recessed below said surface to facilitate bonding with the first package half.

Please add the following new claims:

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24. A PCB package comprising:
first and second stamped metal covers;

first and second plastic frame elements respectively associated with said first and second covers, said metal covers having edges bent to conform to said frames and including fingers embedded in said frames which are injected molded around said fingers; and

the first frame element being sonically bonded to said second plastic frame element.

25. A peripheral device PCB package comprising:
first and second stamped metal covers;

first and second plastic frame elements respectively associated with said first and second stamped metal covers;

the first plastic frame element being bonded to the second plastic frame element to create an integral unit; and

means for securing said first and second metal covers to said first and second plastic frame elements.

26. The package of Claim 25 in which said means comprises edges

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of said first and second metal covers that are bent to conform to a shape of the corresponding first and second frame element and to hold said first and second covers to said first and second plastic frame elements.

27. The package of Claim 26 in which said means further comprises fingers on said first and second covers which are embedded into said first and second plastic frame elements which are injection molded around said fingers.

28. A PCB package comprising:

first and second metal covers, each cover having two edges bent generally in a U-shape, each of the edges including protruding portions, the protruding portions adjacent open portions providing voids;

first and second plastic frame elements respectively associated with the first and second metal covers, each of the plastic frame elements attached to each corresponding metal cover by each frame element having an injection molded portion within the U-shaped edge of each side of each cover and the injection molded portion contained within at least one of said voids on each of the edges of the first and second metal covers in order to provide an integral unit combining the first plastic frame with the first metal cover and the second plastic frame with the second metal cover; and

the first frame element including a raised surface to provide for sonically bonding the first frame element to the second frame element in order to secure the first and second metal covers together.